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Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

 (Currently Amended) A laminate comprising a thermoplastic polyimide layer, and a metal layer on a surface of the thermoplastic polyimide layer,

wherein said thermoplastic polyimide layer is surface-treated by at least one treatment selected from the group consisting of a plasma treatment, a corona treatment, a coupling agent treatment, a permanganate treatment, a ultraviolet ray emitting treatment, an electron beam emitting treatment, surface treatment by colliding an abrasive at a high speed, a firing treatment, and a hydrophilization treatment.

wherein said thermoplastic polyimide layer comprises a thermoplastic polyimide which is obtained by dehydration and ring-closing a polyamic acid represented by the following general formula (1);

wherein A is a quadrivalent organic group selected from the following formula (2), and may be the same or different; X is a divalent organic group selected from the following formula (3), and may be the same or different; B is a quadrivalent organic group other than those represented by the formula (2), and may be the same or different; Y is a divalent organic group other than those represented by the formula (3), and may be the same or different; m: n is 100: 0[i)]] to 50:50;

Formula (2)

2. (Canceled)

- 3. (Previously Presented) The laminate of Claim 1, wherein said thermoplastic polyimide layer is surface-treated by means of an ion our treatment.
- 4. (Previously Presented) The laminate of Claim 3, wherein said ion gun treatment is a treatment using argon ion.
- (Previously Presented) The laminate of Claim 1, wherein said metal layer is formed by depositing a metal element while heating the thermoplastic polyimide layer.
- 6. (Previously Presented) The laminate of Claim 5, wherein a heating temperature is at least 100°C.
- 7. (Previously Presented) The laminate of any one of Claims 1, 3 or 4, wherein said metal layer is an electrolessly plated layer.
- 8. (Previously Presented) The laminate of Claim 6, wherein said metal layer is formed by at least one method selected from the group consisting of a sputtering method, a vacuum vapor deposition method, an ion plating method, an electron beam vapor deposition method, and a chemical vapor deposition method.
- (Previously Presented) The laminate of Claim 8, wherein said metal layer comprises a first metal layer and a second metal layer.
- (Previously Presented) The laminate of Claim 9, wherein said first metal layer comprises nickel, cobalt, chrome, titanium, molybdenum, tungsten, zinc, tin, indium, gold, or an alloy thereof.

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11. (Previously Presented) The laminate of Claim 10, wherein said second metal laver comprises copper or an alloy thereof.

12. (Currently Amended) A laminate comprising

a non-thermoplastic polyimide layer having a thermoplastic polyimide layer on at least one face: and

a metal layer formed on at least one face of surfaces of said thermoplastic polyimide layer,

wherein said thermoplastic polyimide layer is surface-treated by at least one treatment selected from the group consisting of a plasma treatment, a corona treatment, a coupling agent treatment, a permanganate treatment, a ultraviolet ray emitting treatment, an electron beam emitting treatment, surface treatment by colliding an abrasive at a high speed, a firing treatment, and a hydrophilization treatment.

wherein said thermoplastic polyimide layer comprises a thermoplastic polyimide which is obtained by dehydration and ring-closing a polyamic acid represented by the following general formula (1);

wherein A is a quadrivalent organic group selected from the following formula (2), and may be the same or different; X is a divalent organic group selected from the following formula (3), and may be the same or different; B is a quadrivalent organic group other than those represented by the formula (2), and may be the same or different; Y is a divalent organic group other than those represented by the formula (3), and may be the same or different: m: n is 100: 0finil to 50:50:

Formula (2)

$$\begin{array}{c} - \bigcap_{i=1}^{CH_1} - \bigcap_{i=1}^{CH_2} - \bigcap_{i=1}^{CF_2} - \bigcap_{i=1}^{CF_2} - \bigcap_{i=1}^{CF_2} - \bigcap_{i=1}^{CH_2} - \bigcap_{i=1}^{CF_2} - \bigcap_{i=1}^{CF_2}$$

13. (Currently Amended) A laminate comprising a thermoplastic polyimide layer and a metal layer formed on said thermoplastic polyimide layer on one surface, and an adhesive layer on the other face,

wherein said thermoplastic polyimide layer is surface-treated by at least one treatment selected from the group consisting of a plasma treatment, a corona treatment, a coupling agent treatment, a permanganate treatment, a ultraviolet ray emitting treatment, an electron beam emitting treatment, surface treatment by colliding an abrasive at a high speed, a firing treatment, and a hydrophilization treatment,

wherein said thermoplastic polyimide layer comprises a thermoplastic polyimide which is obtained by dehydration and ring-closing a polyamic acid represented by the following general formula (1):

wherein A is a quadrivalent organic group selected from the following formula (2), and may be the same or different; X is a divalent organic group selected from the following formula (3), and may be the same or different; B is a quadrivalent organic group other than those represented by the formula (2), and may be the same or different; Y is a divalent organic group other than those represented by the formula (3), and may be the same or different; m: n is 100: 0[[)] to 50:50;

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14. (Currently Amended) A laminate comprising

a thermoplastic polyimide layer and a metal layer formed on said thermoplastic polyimide layer on one surface, and a copper foil on the other face,

wherein said thermoplastic polyimide layer is surface-treated by at least one treatment selected from the group consisting of a plasma treatment, a corona treatment, a coupling agent treatment, a permanganate treatment, a ultraviolet ray emitting treatment, an electron beam emitting treatment, surface treatment by colliding an abrasive at a high speed, a firing treatment, and a hydrophilization treatment,

wherein said thermoplastic polyimide layer comprises a thermoplastic polyimide which is obtained by dehydration and ring-closing a polyamic acid represented by the following general formula (1):

wherein A is a quadrivalent organic group selected from the following formula (2), and may be the same or different; X is a divalent organic group selected from the following formula (3), and may be the same or different; B is a quadrivalent organic group other than those represented by the formula (2), and may be the same or different: Y is a

divalent organic group other than those represented by the formula (3), and may be the same or different; $m : n \text{ is } 100 : 0[\underline{n}] \text{ to } \underline{50:50}$;

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- 15. (Canceled)
- (Previously Presented) The laminate of any one of Claims 12, 13, or 14, wherein said thermoplastic polyimide layer is surface-treated by an ion gun treatment.
- 17. (Previously Presented) The laminate of Claim 16, wherein said ion gun treatment is a treatment using argon ion.
- 18. (Previously Presented) The laminate of Claim 12, 13, or 14, wherein said metal layer is formed by depositing a metal element while heating the thermoplastic polyimide layer.
- 19. (Previously presented) The laminate of Claim 18, wherein a heating temperature is at least 100°C.
- (Currently Amended) A laminate comprising a polyimide film and a metal layer.

wherein said polyimide film is at least two-layered structure which comprises a non-thermoplastic polyimide layer and a thermoplastic polyimide layer formed on at least one face of the non-thermoplastic polyimide layer; and said metal layer comprises a first metal layer which comprises nickel, cobalt, chrome, titanium, molybdenum, tungsten, zinc, tin, indium, gold, or an alloy thereof, and a second metal layer which comprises copper or an alloy thereof on the first metal layer, wherein said thermoplastic

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polyimide layer is surface-treated by at least one treatment selected from the group consisting of a plasma treatment, a corona treatment, a coupling agent treatment, a permanganate treatment, a ultraviolet ray emitting treatment, an electron beam emitting treatment, surface treatment by colliding an abrasive at a high speed, a firing treatment, and a hydrophilization treatment,

wherein said thermoplastic polyimide layer comprises a thermoplastic polyimide which is obtained by dehydration and ring-closing a polyamic acid represented by the following general formula (1):

wherein A is a quadrivalent organic group selected from the following formula (2), and may be the same or different; X is a divalent organic group selected from the following formula (3), and may be the same or different; B is a quadrivalent organic group other than those represented by the formula (2), and may be the same or different; Y is a divalent organic group other than those represented by the formula (3), and may be the same or different; m: n is 100: 0[f)]] to 50:50;

Formula (2)

$$\begin{array}{c} \overset{C}{\leftarrow} \overset{C}{\leftarrow}$$

21. (Canceled)

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22. (Previously Presented) The laminate of any one of Claims 12, 13, 14, or 20, wherein thickness of said thermoplastic polyimide layer is at least 0.01 μ m to at most 10 μ m, and is thicker than the non-thermoplastic polyimide layer.

23-25. (Canceled)